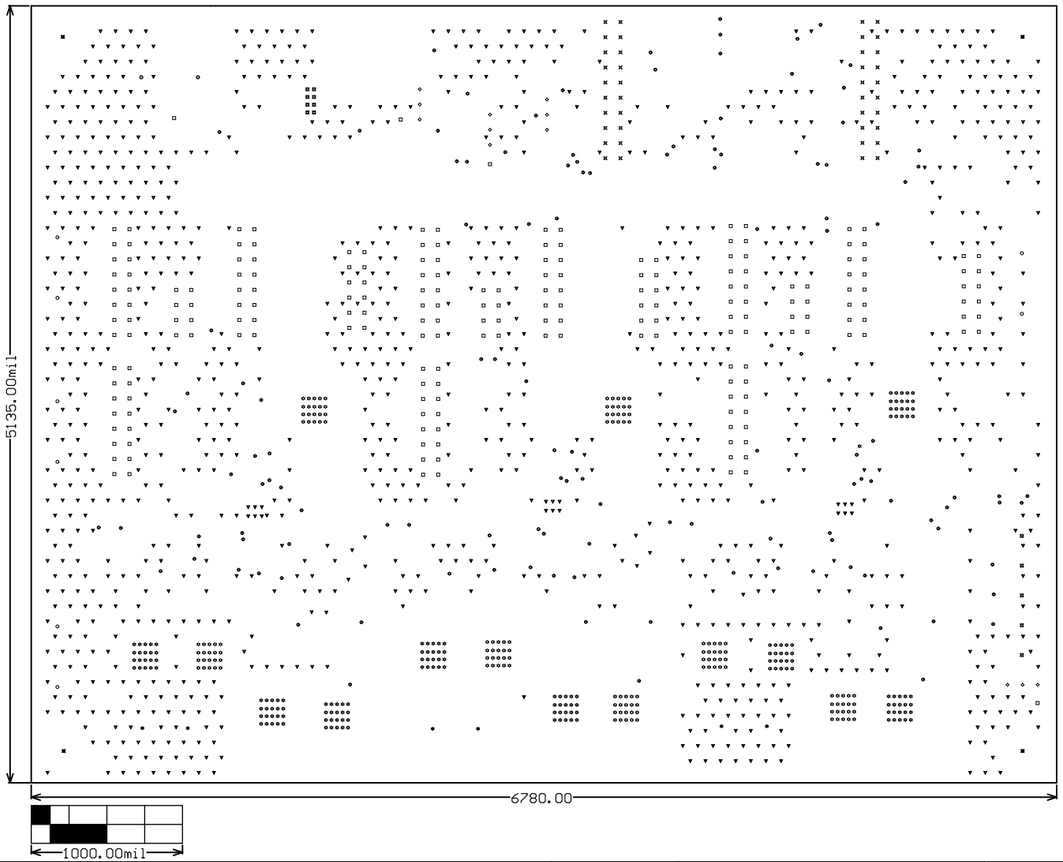
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		2.80mil		
	Dielectric 1	FR-4	8.00mil	4.2	
2	Signal Layer 1		1.40mil		
	Dielectric 2	FR-4	38.40mil	4.2	
3	Signal Layer 2		1.40mil		
	Dielectric 3	FR-4	8.00mil	4.2	
4	Bottom Layer		2.80mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
	8	7,87mil (0,200mm)	PTH	Round	Top Layer - Bottom Layer	
	301	8,00mil (0,203mm)	PTH	Round	Top Layer - Bottom Layer	
	1061	10,00mil (0,254mm)	PTH	Round	Top Layer - Bottom Layer	
	128	16,00mil (0,406mm)	PTH	Round	Top Layer - Bottom Layer	
	208	40,00mil (1,016mm)	PTH	Round	Top Layer - Bottom Layer	
	40	40,16mil (1,020mm)	PTH	Round	Top Layer - Bottom Layer	
	12	45,28mil (1,150mm)	PTH	Round	Top Layer - Bottom Layer	
	5	47,24mil (1,200mm)	PTH	Round	Top Layer - Bottom Layer	
	2	51,18mil (1,300mm)	PTH	Round	Top Layer - Bottom Layer	+/-3,94mil
	8	51,18mil (1,300mm)	PTH	Round	Top Layer - Bottom Layer	
	6	62,99mil (1,600mm)	PTH	Round	Top Layer - Bottom Layer	
	4	125,98mil (3,200mm)	PTH	Round	Top Layer - Bottom Layer	
	1783 Total					

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MD083	REV: A	SUN REV: Not in version control
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 3/13/2024 4:25:34 PM	TEXAS INSTRUMENTS	

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TEXAS INSTRUMENTS

PROJECT TITLE: DRV8161EVM
DESIGNED FOR: Public Release
FILE NAME: MD083A_PCB.PcbDoc

ENGINEER:	LAYOUT BY:
Akshay Rajeev Menon	Akshay Rajeev Menon
SCALE: 1.00	ALTIUM DESIGNER VERSION: 23.1.1.15